

SOT756

plastic single-ended surface-mounted package; 5 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SPAK-5
Package type industry code	SPAK-5
Package style descriptive code	SMS (surface-mounted single in-line)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-2-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.25	-	9.43	9.6	mm
E	package width	8.85	-	9.03	9.2	mm
A	seated height	1.75	-	1.9	2.05	mm
n ₂	actual quantity of termination	-	-	5	-	



2. Package outline

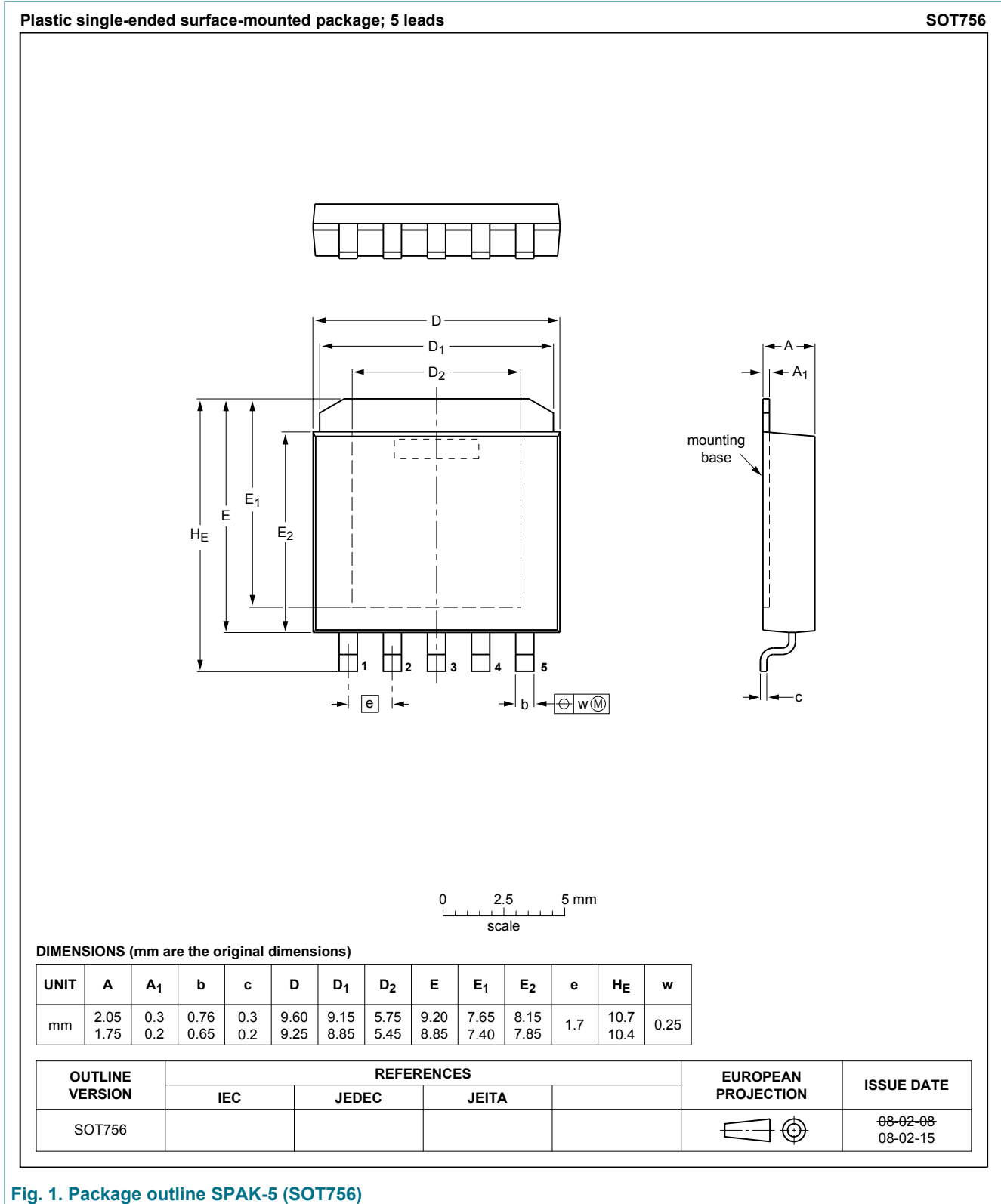


Fig. 1. Package outline SPAK-5 (SOT756)

3. Legal information

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Date of release: 8 February 2016
